

NOT MEASUREMENT SENSITIVE

MIL-S-13949H
SUPPLEMENT 1

16 August 1993

MILITARY SPECIFICATION
SHEET, PRINTED WIRING BOARD

This supplement forms a part of MIL-S-13949H, dated 31 March 1993.

SPECIFICATION SHEETS

- MIL-P-13949/2 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material GB, Glass Base, Woven, Majority Polyfunctional Epoxy Resin, Hot Strength Retention, Copper-Clad.
- MIL-S-13949/4 - Sheet, Printed Wiring Board, Laminated, Base Material GF (Woven E-Glass Reinforcement, Majority Difunctional Epoxy Resin, Flame Resistant, Metal Clad or Unclad).
- MIL-S-13949/5 - Sheet, Printed Wiring Board, Laminated, Base Material GH, (Woven E-Glass Reinforcement, Majority Polyfunctional Epoxy Resin, Hot Strength Retention, Flame Resistant, Metal Clad or Unclad).
- MIL-P-13949/6 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material GP, Glass Base, Non Woven, Polytetrafluoroethylene Resin, Flame Resistant, Copper-Clad.
- MIL-P-13949/7 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material GR, Glass Base, Nonwoven, Polytetrafluoroethylene Resin, Flame Resistant, For Microwave Application, Copper-Clad.
- MIL-P-13949/8 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material GT, Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, Copper-Clad.
- MIL-P-13949/9 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material GX, Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, For Microwave Applications, Copper-Clad.
- MIL-S-13949/10 - Sheet, Printed Wiring Board, Laminated, Base Material GI (Woven E-Glass Reinforcement, Polyimide Resin, Heat Resistant, Metal Clad or Unclad).
- MIL-P-13949/11 - Plastic Sheet, Laminated, Materials (For Printed Wiring Boards), GE Base Material, Glass Fabric, Woven, Majority Difunctional Epoxy Resin Preimpregnated (B-Stage).
- MIL-S-13949/12 - Sheet, Printed Wiring Board, Prepreg, Base Material GF (Woven E-Glass Reinforcement, Majority Difunctional Epoxy Resin, Flame Resistant).
- MIL-S-13949/13 - Sheet, Printed Wiring Board, Prepreg, Base Material GI (Woven E-Glass Reinforcement, Polyimide Resin).
- MIL-P-13949/14 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material GY, Glass Base Woven, Polytetrafluoroethylene Resin, Flame Resistant, For Microwave Application, Copper-Clad.
- MIL-S-13949/15 - Sheet, Printed Wiring Board, Laminated, Base Material AF (Woven Aramid Reinforcement, Epoxy Resin, Flame Resistant, Metal Clad or Unclad).

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- MIL-S-13949/16 - Sheet, Printed Wiring Board, Prepreg, Base Material AF (Woven Aramid Reinforcement, Epoxy Resin, Flame Resistant).
- MIL-P-13949/17 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material AI, Aramid Fabric Woven, Polyimide Resin, Copper-Clad.
- MIL-S-13949/18 - Sheet, Printed Wiring Board, Prepreg, Base Material GH (Woven E-Glass Reinforcement, Majority Polyfunctional Epoxy Resin, Hot Strength Retention, Flame Resistant).
- MIL-P-13949/19 - Plastic Sheet, Laminated, Metal-Clad (For Printed Wiring Boards), Base Material QI, Quartz Base, Woven, Polyimide Resin, Heat Resistant, Copper-Clad.
- MIL-P-13949/20 - Plastic Sheet, Laminated, Materials (For Printed Wiring Boards), Base Material, QI, Quartz Base Woven, Polyimide Resin, Heat Resistant Preimpregnated (B-Stage).
- MIL-P-13949/21 - Plastic Sheet, Laminated, Materials (For Printed Wiring Boards), Base Material, AI, Aramid, Woven, Majority Polyimide Resin Preimpregnated (B-Stage).
- MIL-S-13949/22 - Sheet, Printed Wiring Board, Laminated, Base Material BF (Nonwoven Aramid Reinforcement, Epoxy Resin, Metal Clad or Unclad).
- MIL-S-13949/23 - Sheet, Printed Wiring Board, Prepreg, Base Material BF (Nonwoven Aramid Reinforcement, Epoxy Resin, Flame Resistant).
- MIL-S-13949/24 - Sheet, Printed Wiring Board, Laminated, Base Material GM (Woven E-Glass Reinforcement, Triazine and or Bismaleimide Modified Epoxy Resin, Flame Resistant, Metal Clad or Unclad).
- MIL-S-13949/25 - Sheet, Printed Wiring Board, Laminated, Base Material CF (Nonwoven Polyester, Epoxy Resin, Flame Resistant, Metal Clad or Unclad).
- MIL-S-13949/26 - Sheet, Printed Wiring Board, Prepreg, Base Material GM (Woven E-Glass Reinforcement, Triazine and or Bismaleimide Modified Epoxy Resin).
- MIL-S-13949/27 - Sheet, Printed Wiring Board, Laminated, Base Material SC (Woven S-2 Glass Fiber Reinforcement, Majority Cyanate Ester Resin, Flame Resistant, Metal Clad or Unclad).
- MIL-S-13949/28 - Sheet, Printed Wiring Board, Prepreg, Base Material SC (Woven S-2 Glass Fiber Reinforcement, Majority Cyanate Ester Resin, Flame Resistant).
- MIL-S-13949/29 - Sheet, Printed Wiring Board, Laminated, Base Material GC (Woven E-Glass Reinforcement, Majority Cyanate Ester Resin, Flame Resistant, Metal Clad or Unclad).
- MIL-S-13949/30 - Sheet, Printed Wiring Board, Prepreg, Base Material GC (Woven E-Glass Reinforcement, Majority Cyanate Ester Resin, Flame Resistant).

CONCLUDING MATERIAL

Preparing activity:
Army - ER

Agent:
DLA - ES

(Project 5998-0024-99)